SN <u>10/824,691</u> Docket No. <u>S-102,389</u> In Response to Office Action dated <u>April 22, 2005</u>

AMENDMENTS TO THE CLAIMS:

Please amend the claims as shown below. This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

- 1-5. (cancelled)
- 6. (original) A process for preparing a bulk, superhard, nanocomposite compact consisting essentially of nanocrystalline grains of at least one high-pressure phase of B-C-N surrounded by amorphous, diamond-like carbon grain boundaries, comprising the steps of:
 - (a) ball milling a mixture of graphite and hexagonal boron nitride to produce a mixture of amorphous and/or nanocrystalline graphitic carbon and boron nitride;
 - (b) encapsulating the ball-milled mixture; and
 - (c) sintering the encapsulated ball-milled mixture at a pressure of about 5-25 GPa and a temperature of about 1000-2500 K, thereby producing a bulk, superhard nanocomposite compact consisting essentially of nanocrystalline grains of B-C-N surrounded by amorphous diamond-like carbon grain boundaries.
- 7. (original) The process of claim 6, wherein the ball milled mixture of graphite hexagonal boron nitride consists essentially of about 1-4 parts graphite to about 1 part hexagonal boron nitride.
- 8. (original) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of about 1 part graphite to about 1 part hexagonal boron nitride.
- 9. (original) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of about 2 parts graphite to about 1 part hexagonal boron nitride.
- 10. (original) The process of claim 7, wherein the ball milled mixture of graphite and hexagonal boron nitride consists essentially of 4 parts graphite to about 1 part hexagonal boron nitride.

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- 11. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 10-25 GPa and at a temperature of about 2000-2500 K.
- 12. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 15-25 GPa and at a temperature of about 2000-2500 K.
- 13. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 16-25 GPa and at a temperature of about 2100-2500 K.
- 14. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20-25 GPa and at a temperature of about 2000-2500 GPa.
- 15. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20-25 GPa and at a temperature of about 2100-2400 K.
- 16. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 20 GPa and at a temperature of about 2000-2400 K.
- 17. (original) The process of claim 7, wherein the encapsulated ball-milled mixture is sintered at a pressure of about 25 GPa and at a temperature of about 2100-2300 K.
- 18. (original) The process of claim 6, wherein step (b) comprises encapsulating the amorphous mixture in capsule comprising platinum, gold, rhenium, or boron nitride.
- 19. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 41-68 GPa.
- 20. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 50-68 GPa.
- 21. (original) The process of claim 7, wherein said compact has a Vickers hardness of about 62-68 GPa.
- 22. (original) The process of claim 7, wherein said compact has a Vickers hardness of 68 GPa.

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23-43. (cancelled)